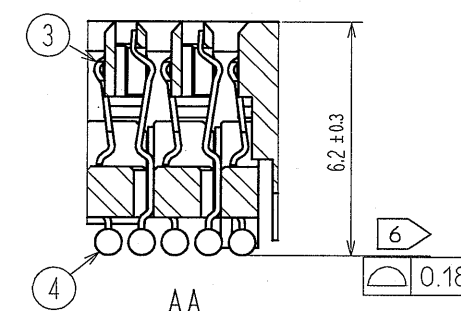
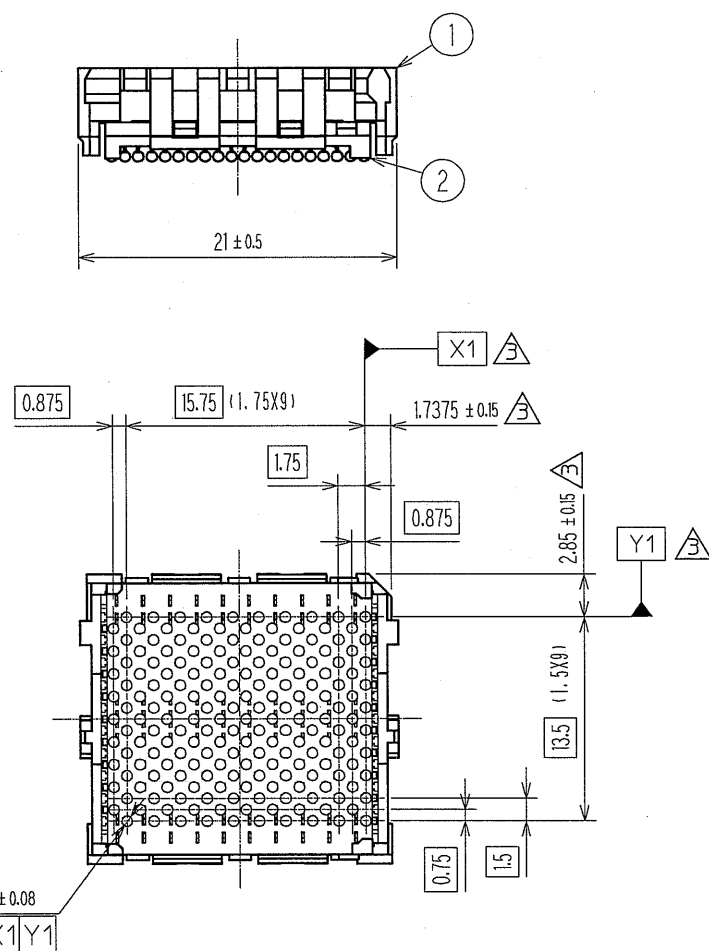




NOTE

- 1 IT3D receptacle to be mated and unmated with IT3-100P-**H(**).
 - 2 Lot no. is marked on top of the connector.
 - 3 Minimum clearance for all devices.
 - 4 Minimum clearance for sensitive devices.
 - 5 More information of this product is available in HIROSE document : ETAD-F0347 "IT3 Design Guideline".
 - 6 Maximum coplanarity of the ball field is 0.18 mm.
 - 7 Standard package of 120pcs are packaged in a carton box.
 - 8 This product is categorized in the MSL2A of IPC/JEDEC J-STD-020B. It is recommended to use within four weeks, defined by JEDEC, in the office environment after unpacked.
 - 9 This product is a solder ball locations and co planarity sensitive BGA connector. It is recommended to handle this product with the automated machine. Solder ball locations and co planarity might be damaged accidentally when it is manually handled by assembly workers.

3	Copper alloy	Contact area : Nickel(1.5 μ m) + Gold(0.76 μ m)		6	NORMEX	TAPE , WHITE
2	LCP	Other area : Nickel(1.5 μ m)		5	HIPS	TRAY , BLACK
1	LCP	BLACK , UL94V-0		4	TIN	Sn(96.5)-Ag(3)-Cu(0.5)
NO.	MATERIAL	FINISH, REMARKS		NO.	MATERIAL	FINISH, REMARKS

UNITS mm		SCALE 2 : 1	REV 	COUNT 3	DESCRIPTION OF REVISIONS DIS-F-004000	DESIGNED T. Saito	CHECKED M. Ezaki	DATE 15, July, 03
 HIROSE ELECTRIC CO., LTD.					APPROVED : T. Matsuo 02/13/2008 CHECKED : T. Matsuo 02/13/2008 DESIGNED : T. Takada 02/13/2008 DRAWN : T. Takada 02/13/2008	DRAWING NO. EDC3-157285-03 PART NO. IT3D-100S-BGA(37) CODE NO. CL636-0013-1-37		

